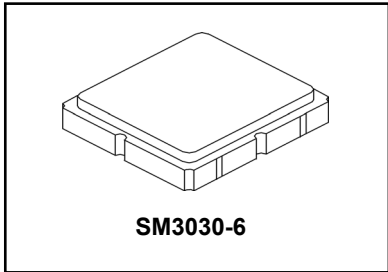


- Surface Mount 3.0 x 3.0 mm Package
- Complies with Directive 2002/95/EC (RoHS)
- Moisture Sensitivity Level: 1

RoHS  
Compliant

SF2186E

1268.52 MHz  
SAW Filter



**Absolute Maximum Ratings**

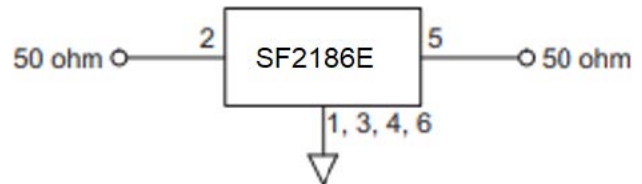
Rating	Value	Units
Input Power Level	10	dBm
DC Voltage on any Non-ground Terminal	3	V
Operating Temperature Range	-40 to +85	°C
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Suitable for Lead-free Soldering - Maximum Soldering Profile	260°C for 30 s	

**Electrical Characteristics**

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	$f_c$			1268.52		MHz
Insertion Loss, 1258.29 to 1278.75 MHz	IL			1.7	3.2	dB
Amplitude Ripple, 1258.29 to 1278.75 MHz				0.5	1.8	
2 dB Bandwidth			20.46	38.3		MHz
Attenuation, Referenced from Minimum IL:						dB
1227.52 MHz			39	45.5		
1309.52 MHz			50	67		
Input/Output VSWR, 1258.29 to 1278.75 MHz				1.3	2.1	
Source Impedance	$Z_s$			50		$\Omega$
Load Impedance	$Z_L$			50		
Case Style	SM3030-6 3.0 x 3.0 mm Nominal Footprint					
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	874, YWWS					

**Electrical Connections**

Connection	Terminals
Input	2
Output	5
Case Ground	All others

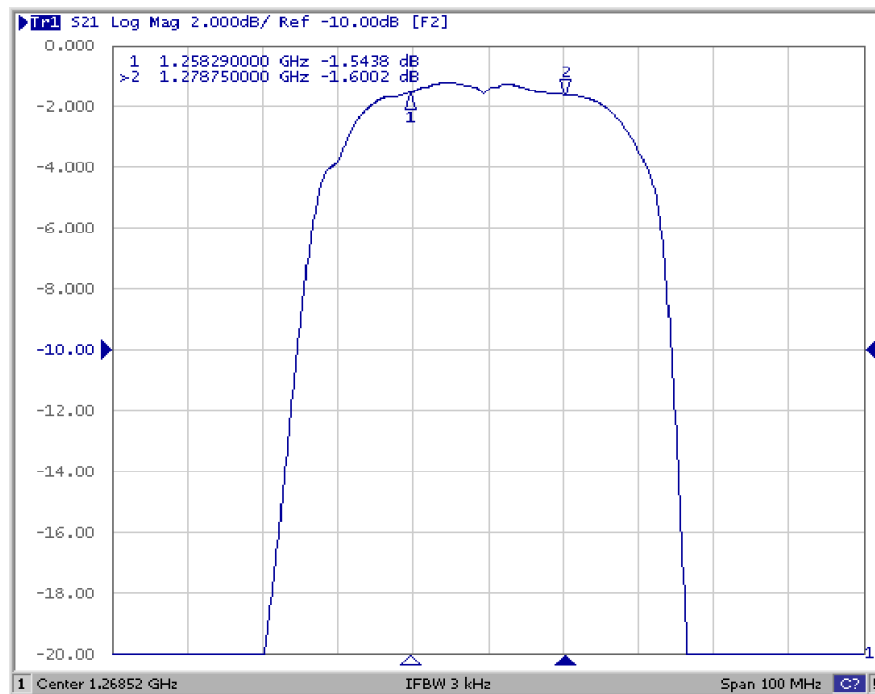


**CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.**

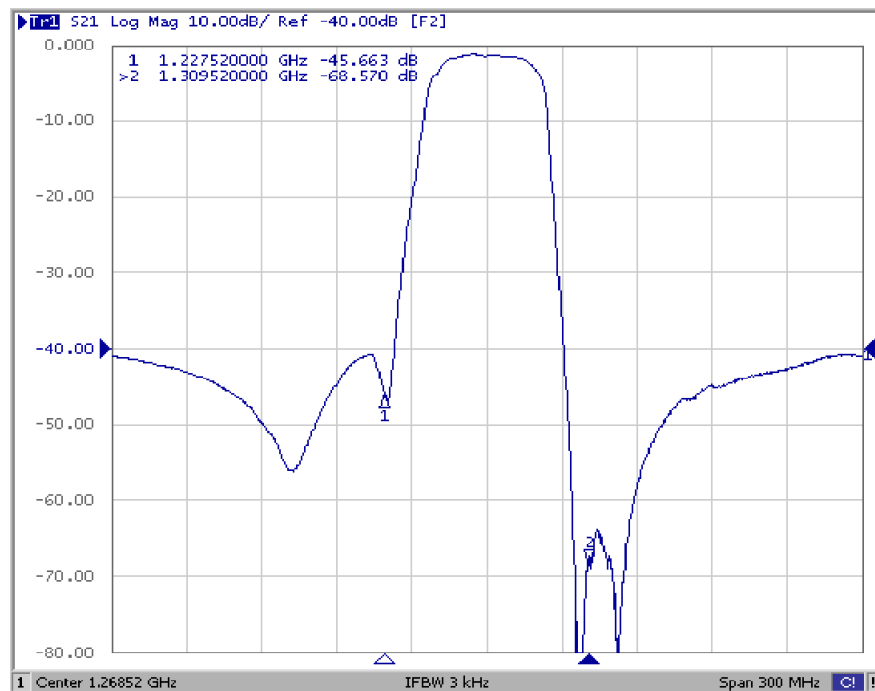
**NOTES:**

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

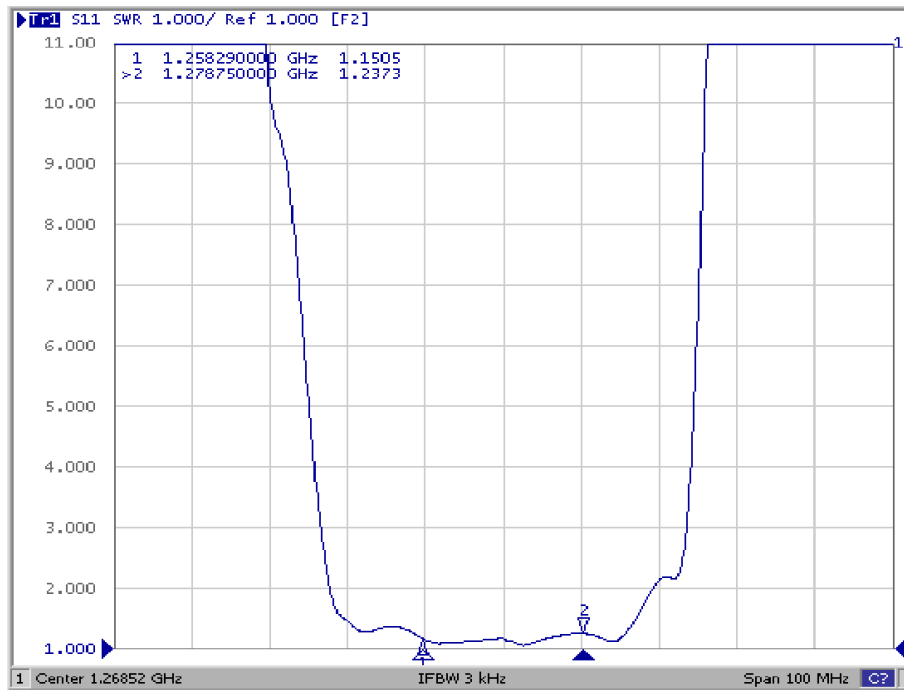
## SF2186E Amplitude Response, 100 MHz Sweep



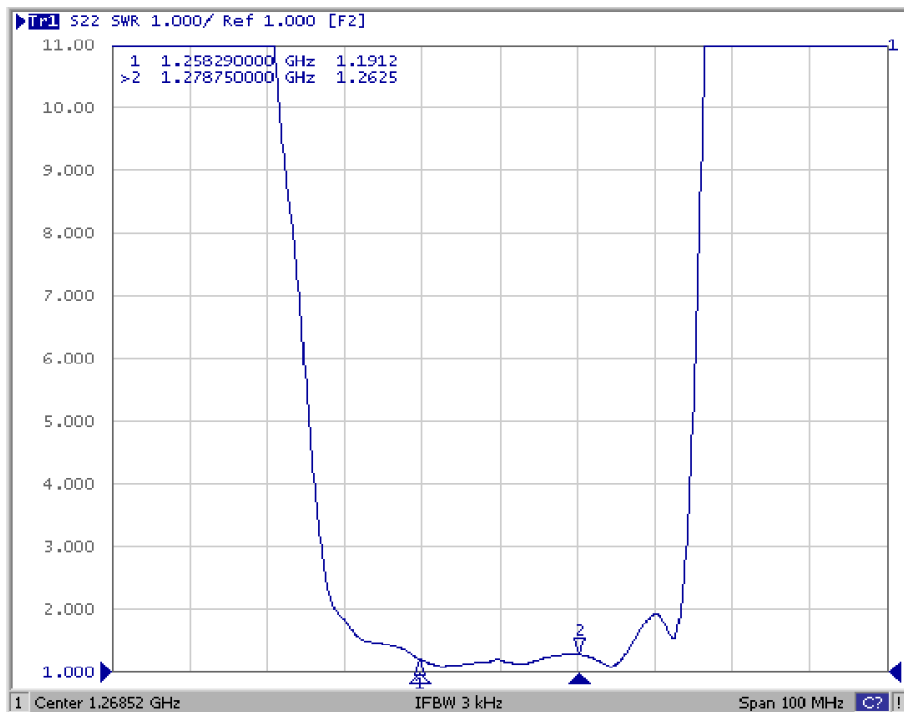
## SF2186E Amplitude Response, 300 MHz Sweep



## SF2186E Input VSWR, 100 MHz Sweep

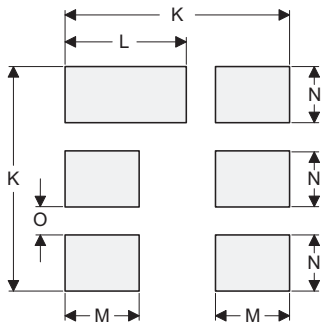
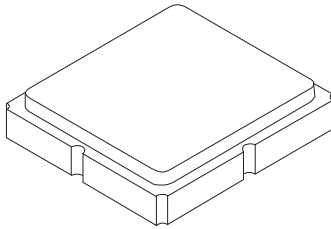


## SF2186E Output VSWR, 100 MHz Sweep



# SM3030-6 Case

## 6-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint



PCB Footprint Top View

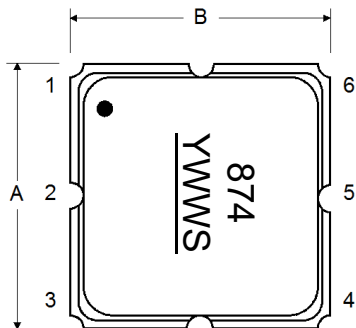
### Case and PCB Footprint Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.00	3.13	0.113	0.118	0.123
B	2.87	3.00	3.13	0.113	0.118	0.123
C	1.12	1.25	1.38	0.044	0.049	0.054
D	0.77	0.90	1.03	0.030	0.035	0.040
E	2.67	2.80	2.93	0.105	0.110	0.115
F	1.47	1.60	1.73	0.058	0.063	0.068
G	0.72	0.85	0.98	0.028	0.033	0.038
H	1.37	1.50	1.63	0.054	0.059	0.064
I	0.47	0.60	0.73	0.019	0.024	0.029
J	1.17	1.30	1.43	0.046	0.051	0.056
K		3.20			0.126	
L		1.70			0.067	
M		1.05			0.041	
N		0.81			0.032	
O		0.38			0.015	

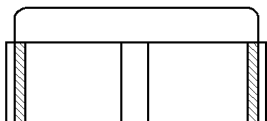
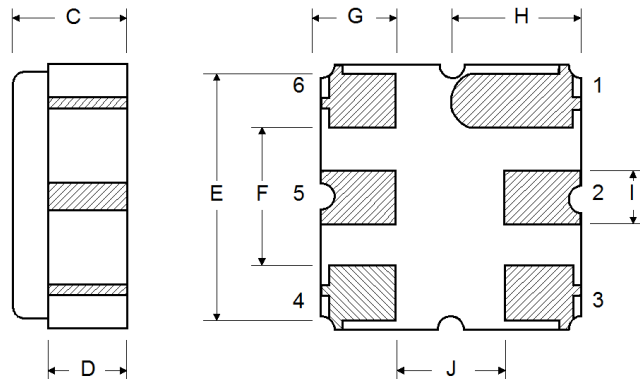
### Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 $\mu\text{m}$ Gold over 1.27 to 8.89 $\mu\text{m}$ Nickel
Lid Plating	2.0 to 3.0 $\mu\text{m}$ Nickel
Body	$\text{Al}_2\text{O}_3$ Ceramic

### TOP VIEW



### BOTTOM VIEW





## Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
4. Time: 5 times maximum.

